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April 14, 2003

To: Examiner Michael Luhrs
USPTO
Art Unit 2824
FAX: 703-746-7473

From: George SimionYour Ref.: 09/843,924Our Ref.: 109182Number of Pages Sent (Including cover sheet): 6Prepared By: gps**Comments:**

Examiner Luhrs,

I have enclosed a copy of the Supplemental Amendment filed in the USPTO on April 11.

Please call if you have any questions regarding the Supplemental Amendment.

Thank you.

George Simion

Sent by: GPS

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PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Kazunori SAKURAI et al.

Group Art Unit: 2824

Application No.: 09/843,924

Examiner: Michael K. Lubrs

Filed: April 30, 2001

Docket No.: 109182

For: METHOD FOR FORMING BUMP, SEMICONDUCTOR DEVICE AND METHOD
FOR MAKING THE SAME, CIRCUIT BOARD, AND ELECTRONIC DEVICE**SUPPLEMENTAL AMENDMENT**Director of the U.S. Patent and Trademark Office
Washington, D.C. 20231

Sir:

As supplement to the Amendment filed February 20, 2003, please further amend the
above-identified application as follows:

IN THE CLAIMS:

Please replace claim 1:

1. (Amended) A method for forming a bump, comprising:
forming a resist layer that defines a through hole which overlaps at least a
portion of a pad;
forming an opening in an insulating film after forming the resist layer, the
opening exposing at least a part of the pad;
forming a metal layer after forming the opening, the metal layer connected to
the portion of the pad exposed at the opening; and
forming a bump connected to the pad after forming the metal layer.